

**Call for Posters,**  
**High-Tech Facility Academic R&D Area Exhibition,**  
**High-Tech Facility International Forum,**  
**SEMICON Taiwan 2024**

Nangang International Exhibition Center, Hall2, Taipei, Taiwan  
September 4~6, 2024

The technical committee of the High-Tech Facility International Forum invites abstracts for poster exhibition during the High-Tech Facility Academic Exhibition, SEMICON Taiwan 2024 on September 4-6, at the Nangang International Exhibition Center, Hall 2, Taipei, Taiwan.

The poster exhibition welcomes researchers from academia and experts from the industry to present their research and early-stage solutions/products to high-tech facility managers. Particularly, we encourage presentations from graduates and newcomers because we want to highlight new talents interested in our industry and provide them with insights for a successful career launch in the high-tech facility industry.

To learn more about the High-Tech Facility International Forum, please go to the forum page found here <https://www.htfa-en.org.tw/2024q3> .

**I. Submission Details:**

There is a two-step submission process:

**Step #1: Submit your abstract (Deadline: July 29, 2024)**

Please fill in the online form by including the following information (in English):

- Presenter information and co-author(s)
- Project/Poster Title (15 words or less)
- Keywords (up to 5)
- Information on the applicant (name, institution, email)
- Project Progress (max. 500 characters, typically 70-130 words)
- Project Needs Assessment (max. 500 characters, typically 70-130 words)
- Project Goals (max. 500 characters, typically 70-130 words)
- Project Educational Strategies/Intervention (max. 500 characters, typically 70-130 words)
- Project Evaluation (max. 500 characters, typically 70-130 words)

**Step #2: Submit your poster  
(after abstract acceptance – Deadline: August 21, 2024)**

After abstract acceptance, participants are invited to submit their posters and to give their consent to make the poster available on the Forum website and High-Tech Facility Academic R&D Area.

Posters should be in English, and contain the following information:

- Title
- Keywords (up to 5)

- Information on the presenter(s) and co-author(s) (name, institution, email)
- Challenge(s) to be addressed
- Action(s) / process in place
- Results and change(s) achieved
- Collaborators involved
- Consent to make the poster available on the Forum website

## II. Poster Topic

We welcome abstracts that relate to the theme "Accelerate Innovation, Empower Smart and Sustainable Facility "

Topics of interest include, but are not limited to:

1. Intelligent Factory
2. Digital Strategy & Management
3. Environmental Sustainability
4. Energy Saving and Carbon Reduction
5. Air Pollution Control
6. Water & Power Resource Management
7. Waste Recycling
8. Corporate ESG
9. Strategies for IT and OT Cyber Security

## III. Important Dates:

- **July 15, 2024 (Monday) 23:59 Poster abstract submission deadline is extended by 2 weeks to July 29, 2024**
- **August 5, 2024 (Monday) Notification of poster review results**
- **August 21, 2024 (Wednesday) Deadline for accepted poster submission**
- **September 4-6, 2024 (Wednesday) 10:00 – 16:00 High-Tech Facility Academic Exhibition DAY1-3**

## IV. Selected posters will receive:

1. One complimentary pass to the High-Tech Facility International Forum 2024
2. For students, an additional pass will be given to their professor
3. High-speed rail Round-trip ticket
4. For students, poster session presentation scholarship

## V. Queries

If you have any queries about the submission process, please feel free to contact the secretariat of the Taiwan High-Tech Facility Association at [peggyho@htfa.org.tw](mailto:peggyho@htfa.org.tw)

## VI. Poster Exhibition Co-Chairs (Last Name Alphabetical Order)

- Shang-Hsien Hsieh, Department of Civil Engineering, National Taiwan University
- Wei-Chih Wang, Department of Civil Engineering, National Yang Ming Chiao Tung University

- Jian-Hong Wu, Department of Civil Engineering, National Cheng Kung University